

P 685



ELAST UNIVERSAL

Elastic adhesive for bonding solid and engineered wood flooring

CHARACTERISTICS

- Suitable for plenty types of wood flooring
- Long-lasting strong bond
- No priming required for most substrates
- With Flextec™ Technologie:
 - Water- and solvent-free
 - Excellent workability
 - Easier removal of stains
 - Durable elastic

SCOPE OF USE

Ceresit P 685 is a very low-emission, single-component special adhesive for bonding:

- strip wood flooring
- mosaic, on-edge lamella and lamparquet
- engineered wood flooring
- solid floorboards, greater than 16 mm thickness and lower than 160 mm width

Ceresit P 685 can be used on:

- mineral screeds
- dry screed constructions, chipboards (V100) and OSB boards
- Ceresit levelling compounds DX, XXL-XPRESS, AS1
- natural stones, tiles and terrazzo.

The elastic bond absorbs shear forces and thus permanently reduces the influence of tensile stresses on the substrate. Flextec® is a user-friendly alternative to conventional PUR adhesives.

Use Ceresit P 685 for bonding solid wood flooring of larger formats, exotic woods and wood block.

Ceresit P 685 meets the highest requirements for indoor air quality and environmental compatibility.

SUBSTRATE PREPARATION

The substrates must comply with the requirements of comparable national standards. In particular, they must be clean, free from structural defects, firm, dry and free of substances which may impair adhesion. New substrates must be thoroughly ground and vacuumed to free them of dust and adhesion separating layers. Nonabsorbent, smooth substrates, e. g. ceramic tile or terrazzo floors, must be cleaned and sanded down and vacuumed if necessary. The wood flooring is bonded on top of those prepared substrates without need for a priming coat. After



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the necessary mechanical preparation prime old substrates and mastic asphalt screeds in any case with Ceresit R 755 or Ceresit R 740. Uneven as well as old substrates must be levelled off with the recommended Ceresit levelling compounds with at least 2 mm thickness.

APPLICATION

Stir the adhesive well and apply it evenly to the substrate with a suitable notched trowel. Only apply as much adhesive as can be laid with wood flooring within the working time. Ensure the backing of the wood flooring is well wetted. Avoid gluing the edges. Allow a minimum gap of 10 mm from walls. Remove the spacer wedges from the perimeter joints immediately after installation. Avoid walking on the parquet surface both during and for at least 24 hours after installation.

PLEASE NOTE

- Best possible indoor air quality after floor installation work requires conformity to the standard working conditions as well as completely dry substrates, primers and leveling compounds.
- Especially multi-layer wood flooring with MDF/HDF middle layer and solid wood flooring without tongue and -groove joint

have a higher tendency to "buckle" with seasonal fluctuations in humidity (e. g. summer/winter change). Elastic adhesives cannot completely prevent such effects. In the above cases, we recommend using Ceresit P 625 to ensure shear-resistant bonding.

- Do not use Ceresit P 685 in direct contact with Ceresit R 777 or Ceresit R 766 water-based primers.
- Remove any skin that may have formed on the product (e.g. caused by improper storage), do not stir it in.
- Prevent the adhesive from penetrating into the wood flooring joints since interaction with any subsequently applied sealing finishes cannot be excluded.
- Carry out floor installation work at floor temperatures above 15 °C, air temperature above 18 °C and the relative humidity below 75 %.
- Immediately remove fresh spots of adhesive with industrial spirit (alcohol).
- Clean the tools also with industrial spirit (alcohol) immediately after use.
- Tightly close opened buckets and use them up as soon as possible.
- The curing time may vary depending on temperature and relative humidity. They will be shorter at higher temperatures and higher humidity, but longer at lower temperatures and lower humidity.

PRODUCT SAFETY

Ceresit P 685 is solvent-free and therefore a suitable alternative to solvent-containing products. Methanol is released during the curing process. Therefore ensure adequate ventilation during the application and drying process. The risk of medium- or long-term release of appreciable concentrations of volatile organic compounds (VOCs) into the ambient air is negligible.

Apart from the information given here it is also important to observe the relevant guidelines and regulations of various organisations and trade associations as well as the respective standards of the German Standards Institute (DIN). The aforementioned characteristics are based on practical experience and applied testing. Warranted properties and possible uses which go beyond those warranted in this information sheet require our written confirmation. All data given was obtained at an ambient and material temperature of +23 °C and 50 % relative air humidity unless specified otherwise. Please note that under other climatic conditions hardening can be accelerated or delayed.

The information contained herein, particularly recommendations for the handling and use of our products, is based on our professional experience. As materials and conditions may vary with each intended application, and thus are beyond our sphere of influence, we strongly recommend that in each case sufficient tests are conducted to check the suitability of our products for their intended use. Legal liability cannot be accepted on the basis of the contents of this data sheet or any verbal advice given, unless there is a case of wilful misconduct or gross negligence on our part. This technical data sheet supersedes all previous editions relevant to this product.

Eating, drinking and smoking should be avoided while working with this product. Wear protective gloves and protective clothing during work.

In case of contact with the eyes or the skin, rinse immediately with plenty of water. In case of contact with the eyes, also consult a doctor.

Information for allergy sufferers on: +49 (0)211 797-0.

Keep out of reach of children.

For professional users.

Safety data sheet available on www.ceresit.com.

GISCODE RS 10 silane-modified polymers, contains methoxy silane

EMICODE EC 1 PLUS R very low-emission according to GEV

DISPOSAL

Do not allow product to reach sewage system or any water course. Do not allow to penetrate the ground/ soil. Only recycle totally empty packages. Dispose of hardened product residues as industrial waste similar to household waste or in the container for commercial/ construction site waste. Dispose of unhardened product residues as hazardous waste.

European waste code number (EWC): 08 04 10.

STORAGE

12 months, cool and dry.

PACKAGING

Plastic bucket 16 kg.

TECHNICAL DATA

Supplied as	beige paste	
Open time	none	
Working time	approx. 30 minutes	
Load bearing	after approx. 24 hours, on non-absorbent substrates after 48 hours	
Sanding work/ surface treatment	after 24 hours at the earliest, on non-absorbent substrates after 48 hours	
Temperature resistance after curing	up to +50 °C, can be used on underfloor heating constructions	
for transport	-20 °C to +50 °C	
for storage	+10 °C to +30 °C	
Impact sound reduction	13 dB acc. to DIN EN 140-8	
Room sound reduction	12 dB	

Consumption:

wood flooring, on-edge lamella (or industrial wood flooring), lamparquet		
notch size B 3	approx. 850 g/m ²	coverage/bucket: 19 m ²
strip wood flooring, multilayer/prefinished wood flooring up to 1200 mm length		
notch size B 11	approx. 1050 g/m ²	coverage/bucket: 15 m ²
larger formats, e.g. floorboards made of solid wood or prefinished wood flooring		
notch size B 15	approx. 1150 g/m ²	coverage/bucket: 14 m ²

The above times were measured under standard climatic conditions

(23 °C/50 % rel. air humidity). Please note that under other climatic conditions curing resp. hardening may be accelerated or delayed.



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Quality for Professionals